

DECLARATION AND POWER OF ATTORNEY FOR ORIGINAL U.S. PATENT APPLICATION

Attorney's Docket No. NVIDP234/P000825

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: PAD OVER ACTIVE CIRCUIT SYSTEM AND METHOD WITH MESHED SUPPORT STRUCTURE, the specification of which,

(check one)

1. ☒ is attached hereto.
2. ☐ was filed on _____ as
U.S. Application Serial No. _____
and was amended on _____.
3. ☐ was filed on _____ as
International PCT Application Serial No. _____
and was amended on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, CFR § 1.56.

I hereby claim foreign priority benefits under Title 35, United States code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Benefits Claimed?

_____ (Appl. No.)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Appl. No.)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Appl. No.)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/> Yes <input type="checkbox"/> No

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

_____ (Application Serial No.)	_____ (Filing Date)
_____ (Application Serial No.)	_____ (Filing Date)

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Attny Docket No. NVIDP234/P000825

Prior U.S. Application(s)

_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status - patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status - patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status - patented, pending, abandoned)

And I hereby appoint Kevin J. Zilka (Reg. No. 41,429); Dominic M. Kotab (Reg. No. 42,762); Richard B. Domingo (Reg. No. 36,784); Stephen H. Pettigrew (Reg. No. 35,978); and Paul D. Carmichael (Reg. No. 18,679) as my principal agents to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Send Correspondence To: **Silicon Valley IP Group, PC**
P.O. BOX 721120
San Jose, California 95172-1120

Direct Telephone Calls To: **Kevin J. Zilka at telephone number (408) 505-5100**

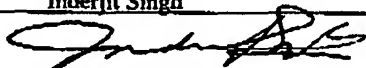
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Typewritten Full Name of
Sole or First Inventor:

Inderjit Singh

Citizenship: MALAYSIA

Inventor's signature:



Date of Signature: 7/31/03

Residence: (City)

Saratoga

(State/Country) CA /USA

Post Office Address:

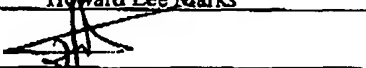
18136 Arroyo Lane, Saratoga, CA 95131

Full Name of Second Joint
Inventor (if any):

Howard Lee Marks

Citizenship: USA

Inventor's signature:



Date of Signature: 7/31/03

Residence: (City)

Gilroy

(State/Country) CA /USA

Post Office Address:

7551 Troon Court, Gilroy, CA 95020

Full Name of Third Joint
Inventor (if any):

Joseph David Greco

Citizenship: USA

Inventor's signature:



Date of Signature: 7/31/03

Residence: (City)

San Jose

(State/Country) CA /USA

Post Office Address:

1254 Serrle Ave., San Jose, CA 95125

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:

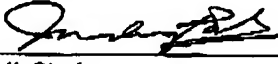
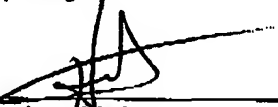

PAD OVER ACTIVE CIRCUIT SYSTEM AND METHOD WITH MESHED SUPPORT STRUCTURE

(Atty. Docket No.: NVIDP234/P000825) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to nVIDIA Corporation, a Delaware corporation having a place of business at 2701 San Tomas Expressway, Santa Clara, California 95050, (hereinafter referred to as ("ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature: 
Typed Name: Inderjit Singh Date: 7/31/03
- 2) Signature: 
Typed Name: Howard Lee Marks Date: 7/31/03
- 3) Signature: 
Typed Name: Joseph David Greco Date: 7/31/03

**ASSIGNMENT RECORDATION COVER SHEET
-PATENTS ONLY-**

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)
 - a) Inderjit Singh
 - b) Howard Lee Marks
 - c) Joseph David Greco
2. Name and address of receiving party(ies):
 - a) Name: NVIDIA Corporation
Address: 2701 San Tomas Expressway
Santa Clara, CA 95050
3. Nature of conveyance

<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name
<input type="checkbox"/> Other _____	<input type="checkbox"/> License Agreement

Execution Date: 7/31/2003

4. Application Number(s) or Patent Number(s): Unassigned

The title of the (new) application is:

**PAD OVER ACTIVE CIRCUIT SYSTEM AND METHOD WITH
MESHED SUPPORT STRUCTURE**

5. Please send all correspondence concerning this (these) documents to:

Silicon Valley IP Group, PC
P.O. Box 721120
San Jose, CA 95172-1120
Tel. No.: (408) 971-2573

6. Total number of applications and patents involved: 1


7. Total fee (37 CFR 3.41): \$40.00

- | | |
|-------------------------------------|--|
| <input checked="" type="checkbox"/> | Enclosed |
| <input type="checkbox"/> | Authorized to be charged to Deposit Account No. 50-1351
(Order No. _____) |

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date:

7/31/03



Dominic M. Kotab
Registration No. 42,762

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